



Material Content Data Sheet



Sales Product Name		BFR 193L3 E6327		Issued		19. July 2018		
MA#		MA001617884						
Package		PG-TSLP-3-1		Weight*		0.54 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.000	0.09		854	
	noble metal	gold	7440-57-5	0.002	0.33		3315	
	inorganic material	silicon	7440-21-3	0.016	2.86	3.28	28609	32778
leadframe	non noble metal	nickel	7440-02-0	0.071	13.10	13.10	130971	130971
wire	noble metal	gold	7440-57-5	0.012	2.14	2.14	21419	21419
encapsulation	inorganic material	antimonytrioxide	1309-64-4	0.000	0.04		393	
	organic material	carbon black	1333-86-4	0.004	0.79		7864	
	plastics	epoxy resin	-	0.058	10.62		106175	
	inorganic material	silicondioxide	60676-86-0	0.366	67.19	78.64	672044	786476
leadfinish	noble metal	gold	7440-57-5	0.008	1.42	1.42	14178	14178
plating	noble metal	gold	7440-57-5	0.008	1.42	1.42	14178	14178
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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